

GreenPAK ™

## **CN363 Smart Power on/off Sequence Controller**

### **General Description**

Renesas SLG7RN46137 is a low power and small form device. The SoC is housed in a 1.6mm x 1.6mm STQFN package which is optimal for using with small devices.

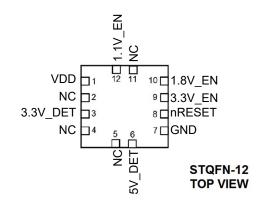
### **Features**

- Low Power Consumption
- Pb Free / RoHS Compliant
- Halogen Free
- STQFN 12 Package

### **Output Summary**

1 Output - Open Drain NMOS 2X 3 Outputs - Push Pull 2X

### **Pin Configuration**





**Pin Configuration** 

Pin#	Pin Name	Туре	Pin Description	Internal Resistor
1	VDD	PWR	Supply Voltage	
2	NC		Keep Floating or Connect to GND	
3	3.3V_DET	Analog Input/Output	Analog Input/Output	floating
4	NC		Keep Floating or Connect to GND	
5	NC		Keep Floating or Connect to GND	
6	5V_DET	Analog Input/Output	Analog Input/Output	floating
7	GND	GND	Ground	
8	nRESET	Digital Output	Open Drain NMOS 2X	floating
9	3.3V_EN	Digital Output	Push Pull 2X	floating
10	1.8V_EN	Digital Output	Push Pull 2X	floating
11	NC		Keep Floating or Connect to GND	
12	1.1V_EN	Digital Output	Push Pull 2X	floating

**Ordering Information** 

Part Number	Package Type						
SLG7RN46137V	V=STQFN-12						
SLG7RN46137VTR	STQFN-12 – Tape and Reel (3k units)						

- 1. Use SLG7RN46137V to order. Shipments are automatically in Tape and Reel.
- 2. "TR" suffix is no longer used. It is a legacy naming convention shown here only for informational purposes.



## **Absolute Maximum Conditions**

Parameter	Min.	Max.	Unit	
Supply Voltage on VDD relative	to GND	-0.5	7	V
DC Input Voltage		GND - 0.5V	VDD + 0.5V	V
Maximum Average or DC Current	Push-Pull 2x	ŀ	17	mA
(Through pin)	OD 2x	ŀ	28	IIIA
Current at Input Pin		-1.0	1.0	mA
Input leakage (Absolute Valu	ue)	ŀ	1000	nA
Storage Temperature Rang	ge	-65	150	° C
Junction Temperature	Junction Temperature			
ESD Protection (Human Body N	2000		V	
ESD Protection (Charged Device	1000		V	
Moisture Sensitivity Level	•	1	·	

### **Electrical Characteristics**

Symbol	Parameter	Condition/Note	Min.	Тур.	Max.	Unit
$V_{DD}$	Supply Voltage		2	5	5.5	V
TA	Operating Temperature		-40	25	85	° C
C <sub>VDD</sub>	Capacitor Value at VDD			0.1	-	μF
Cin	Input Capacitance			4	-	pF
ΙQ	Quiescent Current	Static inputs and floating outputs		72	-	μA
Vo	Maximal Voltage Applied to any PIN in High-Impedance State				VDD	V
	Maximum Average or DC	T <sub>J</sub> = 85°C			73	mA
I <sub>VDD</sub>	Current Through VDD Pin (Per chip side, see Note 2)	T <sub>J</sub> = 110°C			35	mA
	Maximum Average or DC	$T_J = 85^{\circ}C$			92	mA
I <sub>GND</sub>	Current Through GND Pin (Per chip side, see Note 2)	T <sub>J</sub> = 110°C			44	mA
		Push-Pull 2X, Open Drain PMOS 2X, Іон=100µA, at VDD=1.8V	1.702	1.8		V
Vон	HIGH-Level Output Voltage	Push-Pull 2X, Open Drain PMOS 2X, Iон=3mA, at VDD=3.3V	2.87	3.19		V
		Push-Pull 2X, Open Drain PMOS 2X, I <sub>OH</sub> =5mA, at VDD=5.0V	4.3	4.86	1	V
		Push-Pull 2X, IoL=100µA, at VDD=1.8V		0.01	0.02	V
		Push-Pull 2X, IoL=3mA, at VDD=3.3V		0.09	0.13	V
	LOW-Level Output Voltage	Push-Pull 2X, I <sub>OL</sub> =5mA, at VDD=5.0V		0.12	0.16	V
Vol		Open Drain NMOS 2X, I <sub>OL</sub> =100µA, at VDD=1.8V		0.01	0.01	V
		Open Drain NMOS 2X, I <sub>OL</sub> =3mA, at VDD=3.3V		0.05	0.07	V
		Open Drain NMOS 2X, IoL=5mA, at VDD=5.0V		0.07	0.09	V
la	HIGH-Level Output Current	Push-Pull 2X, Open Drain PMOS 2X, VoH=VDD-0.2V, at VDD=1.8V	2.15	2.71		mA
Іон	(Note 1)	Push-Pull 2X, Open Drain PMOS 2X, V <sub>OH</sub> =2.4V, at VDD=3.3V	11.264	19.66		mA



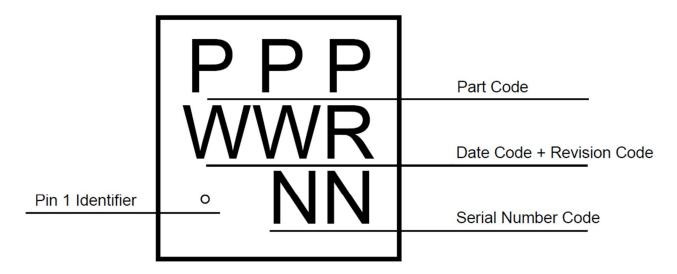
		T =		1	1	
		Push-Pull 2X, Open Drain PMOS 2X, V <sub>OH</sub> =2.4V, at VDD=5.0V	40.598	56.08		mA
		Push-Pull 2X, V <sub>OL</sub> =0.15V, at VDD=1.8V	1.52	2.66		mA
		Push-Pull 2X, V <sub>OL</sub> =0.4V, at VDD=3.3V	8.13	12.36		mA
		Push-Pull 2X, V <sub>OL</sub> =0.4V, at VDD=5.0V	11.59	19.46		mA
I <sub>OL</sub>	LOW-Level Output Current	Open Drain NMOS 2X, V <sub>OL</sub> =0.15V, at VDD=1.8V	3.06	5.13		mA
	(Note 1)	Open Drain NMOS 2X, V <sub>OL</sub> =0.4V, at VDD=3.3V	16.26	22.9		mA
		Open Drain NMOS 2X, V <sub>OL</sub> =0.4V, at VDD=5.0V	19.12	35.621		mA
T <sub>DLY1</sub>	Delay1 Time	At temperature 25°C	185.9	200	232.1	μs
I DLY1	Delay i Tillie	At temperature -40 +85°C (Note 3)	179.7	200	326.3	μs
T <sub>DLY2</sub>	Delay2 Time	At temperature 25°C	185.9	200	232.1	μs
I DLY2	Delay2 Time	At temperature -40 +85°C (Note 3)	179.7	200	326.3	μs
<b>T</b>	Dolov2 Time	At temperature 25°C	185.9	200	232.1	μs
T <sub>DLY3</sub>	Delay3 Time	At temperature -40 +85°C (Note 3)	179.7	200	326.3	μs
_	Counter0 Period	At temperature 25°C	1.87	2	2.25	ms
T <sub>CNT0</sub>	Countero Period	At temperature -40 +85°C (Note 3)	1.8	2	3.18	ms
		Low to High transition, at temperature 25°C	1173		1273	mV
	Analog Comparator0 Threshold Voltage	Low to High transition, at temperature -40 +85°C (Note 3)	1143		1283	mV
V <sub>ACMP0</sub>		High to Low transition, at temperature 25°C	1135		1224	mV
		High to Low transition, at temperature -40 +85°C (Note 3)	1104		1235	mV
		Low to High transition, at temperature 25°C	1173		1269	mV
	Analog Comparator1	Low to High transition, at temperature -40 +85°C (Note 3)	1145		1278	mV
V <sub>ACMP1</sub>	Threshold Voltage	High to Low transition, at temperature 25°C	1132		1231	mV
		High to Low transition, at temperature -40 +85°C (Note 3)	1100		1237	mV
		ACMP 0 at temperature 25°C		50		mV
V <sub>HYST</sub>	Analog Comparator	ACMP 0 at temperature -40 +85°C		50		mV
VHYSI	Hysteresis Voltage (Note 3)	ACMP 1 at temperature 25°C		50		mV
		ACMP 1 at temperature -40 +85°C		50		mV
Tsu	Startup Time	From VDD rising past 1.35 V		0.27		ms
PONTHR	Power On Threshold	V <sub>DD</sub> Level Required to Start Up the Chip	1.182	1.346	1.505	V
POFF <sub>THR</sub>	Power Off Threshold	V <sub>DD</sub> Level Required to Switch Off the Chip	0.752	0.918	1.11	V

#### Note

- 1. DC or average current through any pin should not exceed value given in Absolute Maximum Conditions.
- 2. The GreenPAK's power rails are divided in two sides. Pins 2, 3, 4 and 6 are connected to one side, pins 8, 9, 10 and 12 to another.
- 3. Guaranteed by Design.



## **Package Top Marking**



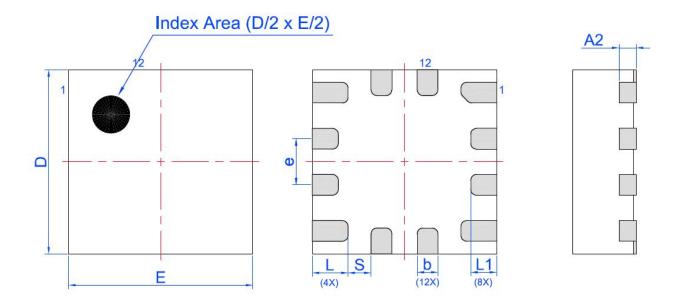
Datasheet Revision	Programming Code Number	Lock Status	Checksum	Part Code	Revision	Date
1.00	002	Ш	0xF73C6A3C	1AN	В	12/12/2022

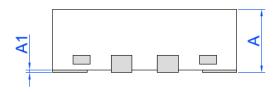
The IC security bit is locked/set for code security for production unless otherwise specified. The Programming Code Number is not changed based on the choice of locked vs. unlocked status.



## **Package Drawing and Dimensions**

12 Lead STQFN FC Package 1.6 x 1.6 mm IC net weight: 0.0028 g





### Unit: mm

Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
Α	0.50	0.55	0.60	D	1.55	1.60	1.65
A1	0.005	-	0.060	E	1.55	1.60	1.65
A2	0.10	0.15	0.20	L	0.26	0.31	0.36
b	0.13	0.18	0.23	L1	0.175	0.225	0.275
е	0.40 BSC			S		0.2 REF	

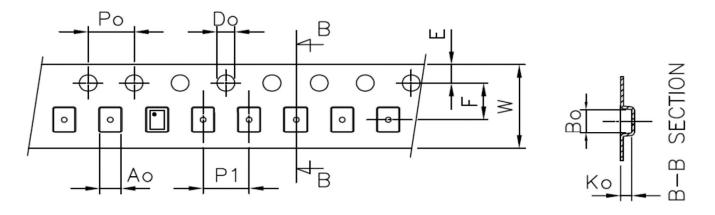


## **Tape and Reel Specification**

		Nominal	Max	Units		Leader (min)		Trailer (min)		Tape	Part
Package Type	# of Pins	Package Size [mm]	per Reel	per Box	Reel & Hub Size [mm]	Pockets	Length [mm]	Pockets	Length [mm]	Width [mm]	Pitch [mm]
STQFN 12L FC 0.4P Green	12	1.6x1.6x0.55	3000	3000	178/60	100	400	100	400	8	4

## **Carrier Tape Drawing and Dimensions**

Package Type	Pocket BTM Length	Pocket BTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge	Index Hole to Pocket Center	Tape Width
	A0	В0	K0	P0	P1	D0	ш	F	W
STQFN 12L FC 0.4P Green	1.8±0.05	1.8±0.05	±0.7	4	4	1.5	1.75	3.5	8



## **Recommended Reflow Soldering Profile**

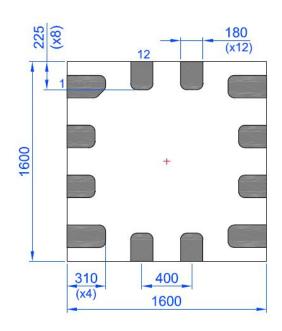
Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 1.408 mm³ (nominal). More information can be found at <a href="https://www.jedec.org">www.jedec.org</a>.

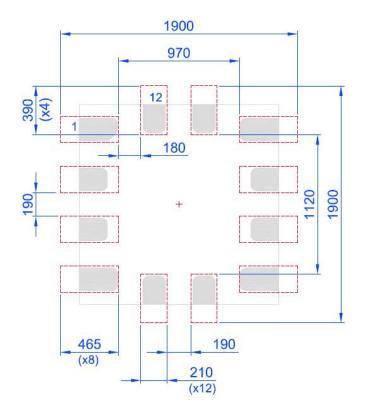
### **Recommended Land Pattern**

Exposed Pad (PKG face down)

Recommended Land Pattern (PKG face down)

## Units: µm







## **Datasheet Revision History**

Date	Version	Change			
11/09/2022	0.10	New design for SLG46110 chip			
11/14/2022	0.11	Updated Device Revision Table			
11/18/2022	0.12	Change VDD range to 2.0~5.5V			
11/17/2022	0.13	Updated Device Revision Table			
12/12/2022	1.00	Production Release			

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